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2. The second of these is the possibility of a change in the direction of the flow of the river. This is a possibility which is not to be overlooked. It is a possibility which is not to be overlooked. It is a possibility which is not to be overlooked.

3. The third of these is the possibility of a change in the direction of the flow of the river. This is a possibility which is not to be overlooked. It is a possibility which is not to be overlooked. It is a possibility which is not to be overlooked.

4. The fourth of these is the possibility of a change in the direction of the flow of the river. This is a possibility which is not to be overlooked. It is a possibility which is not to be overlooked. It is a possibility which is not to be overlooked.

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US PAT-NO: 6362023

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\*\*See image for Certificate of Correction\*\*

TITLE: Dielectric based anti fuse cell with  
polysilicon contact  
plug and method for its manufacture

KWIC

Claims Text CLTX 7 :

7. A method for forming an anti fuse cell array comprising the steps of:  
providing a semiconductor substrate; forming a first insulating layer on the surface of the semiconductor substrate; forming a plurality of doped polysilicon poly 1 lines on the insulating layer; forming a second insulating layer over the plurality of poly 1 lines; creating a plurality of contact openings through the second insulating layer and extending at least partially into the plurality of poly 1 lines, the plurality of contact openings exposing a portion of the plurality of poly 1 lines; forming a doped polysilicon plug layer on the second insulating layer and filling the plurality of contact openings; removing the doped polysilicon plug layer from the second insulating layer while leaving the doped polysilicon plug layer filling the plurality of contact openings, thereby forming a plurality of doped polysilicon contact plug; forming a dielectric layer on the second insulating layer and on the plurality of doped polysilicon contact plug; and forming a plurality of second doped polysilicon poly 2 lines on the dielectric layer.

US PAT NO: 5635316

DOCUMENT IDENTIFIER: US 5635316 A  
\*\*See image for Certificate of Correction\*\*

TITLE: Layout methodology, mask set, and  
patterning method for  
phase shifting lithography

KWIC

Brief Summary Text BSTX 18 :

A method of producing a device layer layout is disclosed. A plurality of lines are defined, and the device features are placed on the lines. In this way, a phase edge or single edge feature mask can be produced from the layout to pattern an image corresponding to the lines. A second mask having the device features overlying the lines is also produced from the layout and is used to preserve wanted portions of the image and to remove unwanted portions of the image.

Detailed Description Text DETX 18 :

The present invention may be used to produce a layout to form small dimension openings in a photosensitive layer, which may be used to form, for example, contact or via openings. Referring to FIG. 9, a plurality of contact openings 901 are defined on the intersection of the plurality of vertical lines 920 927, and horizontal lines 930 936. As described earlier, the lines may be pre-defined or may be defined as the contacts are defined. In addition, the lines need not necessarily be periodic and need not necessarily be orthogonal as shown. In the embodiment shown herein, note that the

contacts are defined over intersections of the lines. As will be seen, this ensures that the phase edge layers and device feature layer may automatically be extracted from the database to produce the appropriate masks. Generally, it may be possible to use the same lines as those used for the layer to which contact is being made. Some additional lines may need to be defined in the contact layer to produce intersections at each contact opening, where, for example, a contact overlies a portion of an underlying line not at an intersection. For example, referring back to FIG. 5, if it were desired to contact line 503, it would be necessary to add a line intersecting line 524 at some point along line 524 where feature 503 is present to produce an intersection. Furthermore, the contact layer need not necessarily have all the lines of the underlying layer, as the underlying layer typically has a greater density of features than the contact layer.

Detailed Description Text : DETX 22 :

Next, the photosensitive layer is exposed to a mask having the features 901 disposed at those intersections where contact openings are desired. After this exposure and development, contact openings will be present as shown in FIG. 12, as all other regions of the photoresist layer are substantially exposed in one or more of the above described three exposures. Again, it will be appreciated that the masks 1000, 1100, and the mask having the features 901 may be exposed in any order. As shown in FIG. 13, a plurality of contact openings 1301 are formed in the photosensitive layer in the regions underneath the features 901. Again, only some of the contact openings 1301 are labeled for clarity.

Detailed Description Text - DETX 26 :

As described herein, the present invention comprises defining a plurality of lines which, depending upon the features, may be arranged in rows and/or columns. The definition of the lines may be done in a variety of manners. In one embodiment, lines may be pre defined with respect to the earlier described grid points in relation to which features are typically defined. For example, in one embodiment the lines may be laid out in rows and columns spaced at approximately the minimum pitch. Features can then be placed on these lines as they are encountered by the system. Alternatively, lines can be defined as features are created. In this embodiment, it should be ensured that no two lines are spaced closer than approximately the minimum pitch, although lines may be placed apart greater than the minimum.

Claims Text CLTX 6 :

defining said plurality of lines;

US PAT NO: 6465298

DOCUMENT IDENTIFIER: US 6465298 B2

\*\*See image for Certificate of Correction\*\*

TITLE: Method of fabricating a  
semiconductor on insulator  
memory cell with buried word and body  
lines

KWIC

Brief Summary Text BSTX 14 :

Another embodiment of the present invention provides a semiconductor memory device, including a memory array. The memory array includes a plurality of bit lines, a plurality of word lines, and a plurality of memory cells. Each memory cell includes an access transistor having a gate region, a body region, and first and second source/drain regions. Each memory cell includes a storage capacitor that is electrically coupled to the second source/drain region of the access transistor. Access circuitry is provided for accessing the memory cells. A plurality of isolation trenches is provided, including a first trench between first and second access transistors and a second trench between the second and third access transistors. A first one of the word lines is located in the first trench at a height that is no higher than the upper surface of the access transistor. The first word line is electrically coupled to the gate regions of the first and second access transistors. A first one of the body lines is located in the second trench at a height that is no higher than the upper surface of the access transistor. The first body line is electrically

coupled to the body portions of the second and third access transistors. A first one of the bit lines is coupled to the first source/drain region of each of the first, second and third access transistors.

Claims Text CLTX 8 :

8. The method of claim 1, including: interposing an insulating layer between the body line and the second trench; forming a **plurality of contact openings** through the insulating layer between the body line and the body regions of the access transistors; and forming contacts in the contact openings for electrically coupling the body line and the body regions of the access transistors.

Claims Text CLTX 20 :

20. A method of fabricating a memory array on a semiconductor substrate, comprising: forming at least first and second trenches in the substrate to define a bar of semiconductor material; forming an insulating layer between the bar and the substrate for providing electrical isolation therebetween; defining a plurality of active areas of semiconductor material on the bar; producing an access transistor in each of the active areas, each access transistor including gate, body, and first and second source/drain regions; forming a buried word line; coupling the word line to the gate region of at least one of the access transistors; forming a buried body line; electrically connecting the body line to the body region of at least one of the access transistors; forming a **plurality of contact openings** through an insulating layer between the buried body line and the body regions of the access transistors; and forming contacts in the contact openings for electrically



coupling the buried body line and the body regions of the access transistors.